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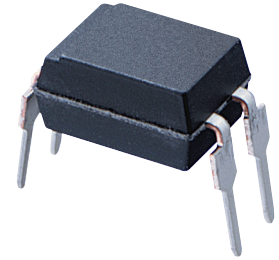
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PC814X Series

DIP 4pin AC Input Photocoupler

*4-channel package type is also available.
(model No. **PC844X Series**)



■ Description

PC814X Series contains an IRED optically coupled to a phototransistor.

It is packaged in a 4pin DIP, available in SMT gullwing lead-form option.

Input-output isolation voltage(rms) is 5.0kV.

Collector-emitter voltage is 80V(*) and CTR is 20% to 300% at input current of $\pm 1\text{mA}$.

■ Features

1. 4pin DIP package
2. Double transfer mold package (Ideal for Flow Soldering)
3. AC input type
4. High collector-emitter voltage ($V_{\text{CEO}} : 80\text{V}^{(*)}$)
5. Current transfer ratio (CTR : MIN. 20% at $I_{\text{F}} = \pm 1\text{mA}$, $V_{\text{CE}} = 5\text{V}$)
6. High isolation voltage between input and output ($V_{\text{iso(rms)}} : 5.0\text{ kV}$)

(*) Up to Date code "P7" (July 2002) $V_{\text{CEO}} : 35\text{V}$.
From the production Date code "J5" (May 1997) to "P7" (July 2002), however the products were screened by $BV_{\text{CEO}} \geq 70\text{V}$.

■ Agency approvals/Compliance

1. Recognized by UL1577, file No. E64380 (as model No. **PC814**)
2. Package resin : UL flammability grade (94V-0)

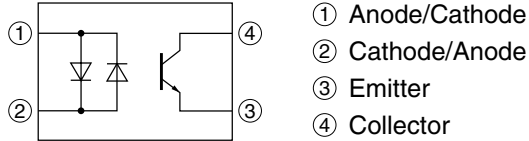
■ Applications

1. Programmable controllers
2. Telephone sets, telephone exchangers
3. System appliances
4. Signal transmission between circuits of different potentials and impedances

Notice The content of data sheet is subject to change without prior notice.

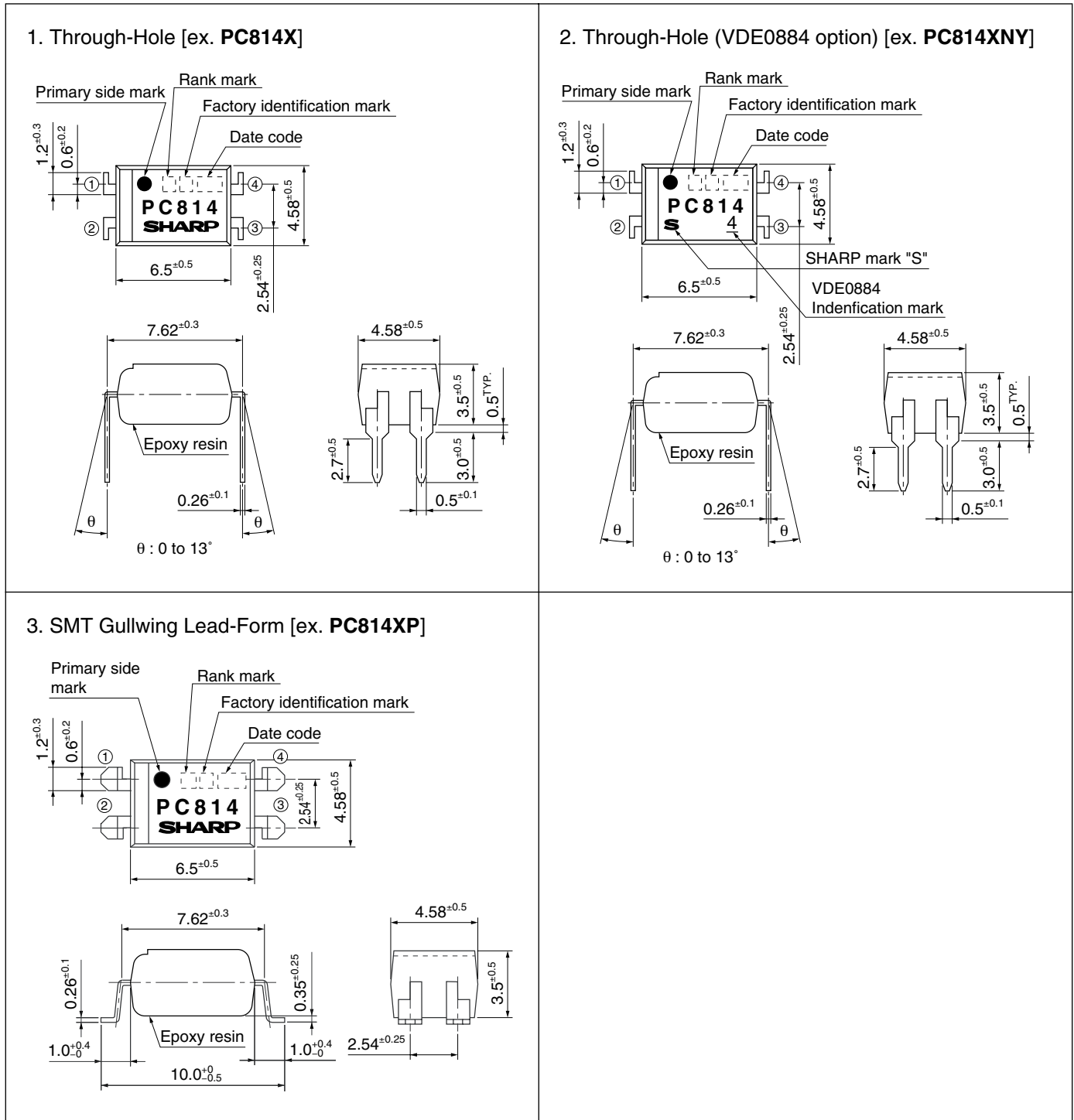
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■ Internal Connection Diagram



■ Outline Dimensions

(Unit : mm)







Product mass : approx. 0.25g

Date code (2 digit)

1st digit				2nd digit	
Year of production				Month of production	
A.D.	Mark	A.D.	Mark	Month	Mark
1990	A	2002	P	January	1
1991	B	2003	R	February	2
1992	C	2004	S	March	3
1993	D	2005	T	April	4
1994	E	2006	U	May	5
1995	F	2007	V	June	6
1996	H	2008	W	July	7
1997	J	2009	X	August	8
1998	K	2010	A	September	9
1999	L	2011	B	October	O
2000	M	2012	C	November	N
2001	N	∴	∴	December	D

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin
no mark	Japan
	
	Indonesia
	Philippines
	China

* This factory marking is for identification purpose only.
Please contact the local SHARP sales representative to see the actual status of the production.

Rank mark

Refer to the Model Line-up table

■ Absolute Maximum Ratings (T_a=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	±50	mA
	*1 Peak forward current	I _{FM}	±1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V _{CEO}	*4 80	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	50	mA
	Collector power dissipation	P _C	150	mW
	Total power dissipation	P _{tot}	200	mW
	*2 Isolation voltage	V _{iso (rms)}	5.0	kV
	Operating temperature	T _{opr}	-30 to +100	°C
	Storage temperature	T _{stg}	-55 to +125	°C
	*3 Soldering temperature	T _{sol}	260	°C

*1 Pulse width ≤ 100μs, Duty ratio : 0.001

*2 40 to 60%RH, AC for 1 minute, f=60Hz

*3 For 10s

*4 Up to Date code "P7" (July 2002) V_{CEO} : 35V.

■ Electro-optical Characteristics (T_a=25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F =±20mA	-	1.2	1.4	V
	Peak forward voltage	V _{FM}	I _{FM} =±0.5A	-	-	3.0	V
	Terminal capacitance	C _t	V=0, f=1kHz	-	30	250	pF
Output	Collector dark current	I _{CEO}	V _{CE} =50V, I _F =0	-	-	100	nA
	Collector-emitter breakdown voltage	BV _{CEO}	I _C =0.1mA, I _F =0	*5 80	-	-	V
	Emitter-collector breakdown voltage	BV _{ECO}	I _E =10μA, I _F =0	6	-	-	V
Transfer characteristics	Collector current	I _C	I _F =±1mA, V _{CE} =5V	0.2	-	3.0	mA
	Collector-emitter saturation voltage	V _{CE (sat)}	I _F =±20mA, I _C =1mA	-	0.1	0.2	V
	Isolation resistance	R _{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	-	Ω
	Floating capacitance	C _f	V=0, f=1MHz	-	0.6	1.0	pF
	Cutt-off frequency	f _C	V _{CE} =5V, I _C =2mA, R _L =100Ω, -3dB	15	80	-	kHz
	Response time	Rise time Fall time	t _r t _f	V _{CE} =2V, I _C =2mA, R _L =100Ω	- -	4 3	18 18

*5 From the production Date code "J5" (May 1997) to "P7" (July 2002), however the products were screened by BV_{CEO} ≥ 70V.

■ Model Line-up

Lead Form	Through-Hole		SMT Gullwing	Rank mark	I _C [mA] (I _F =±1mA, V _{CE} =5V, T _a =25°C)
Package	Sleeve		Taping		
	100pcs/sleeve		2 000pcs/reel		
VDE0884	-	Approved	-		
Model No.	PC814X	PC814XNY	PC814XP	with or without	0.2 to 3.0
	PC814X1	PC814X1Y	PC814XP1	A	0.5 to 1.5

Please contact a local SHARP sales representative to inquire about production status and Lead-Free options.

Fig.1 Forward Current vs. Ambient Temperature

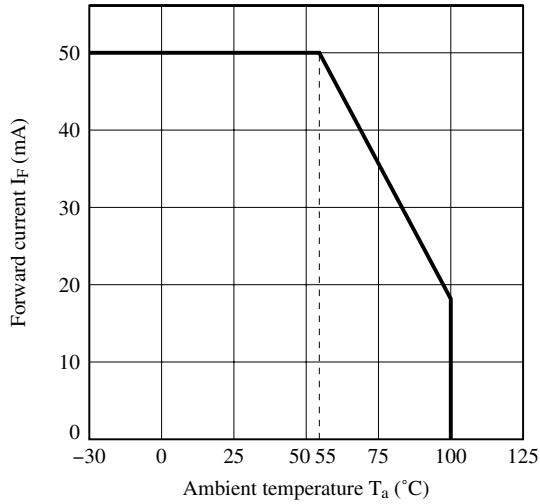


Fig.2 Diode Power Dissipation vs. Ambient Temperature

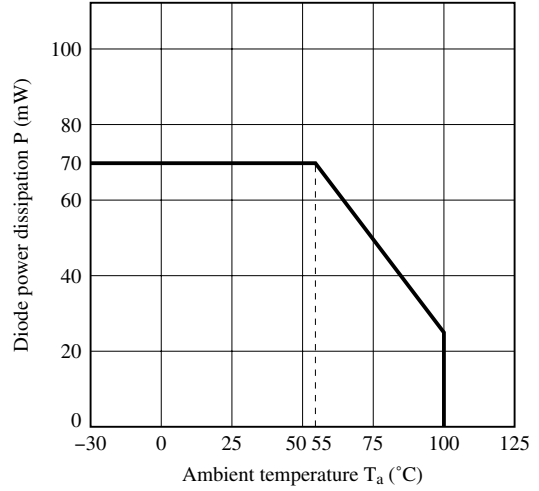


Fig.3 Collector Power Dissipation vs. Ambient Temperature

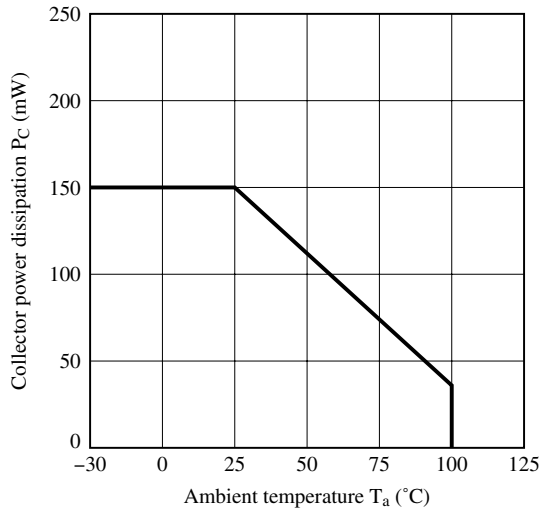


Fig.4 Total Power Dissipation vs. Ambient Temperature

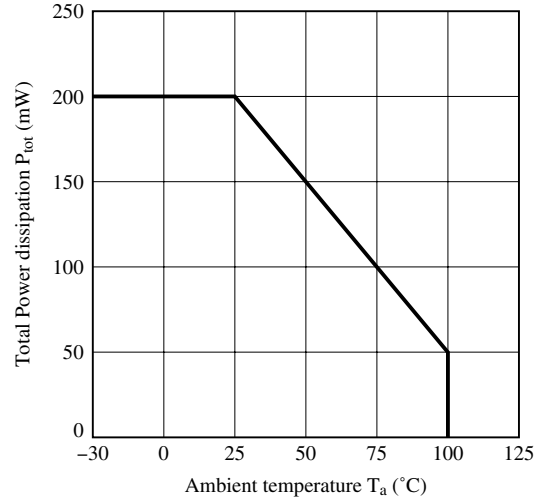


Fig.5 Peak Forward Current vs. Duty Ratio

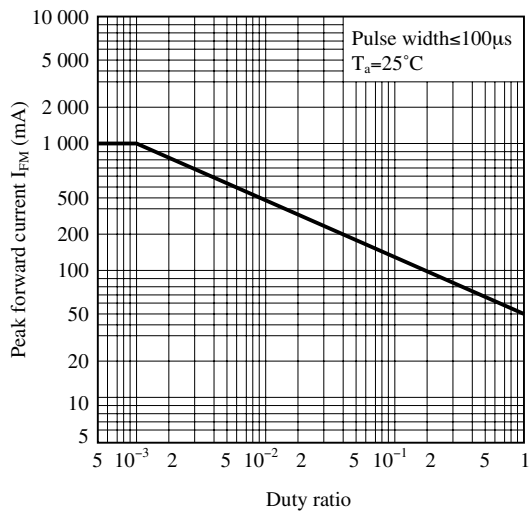


Fig.6 Forward Current vs. Forward Voltage

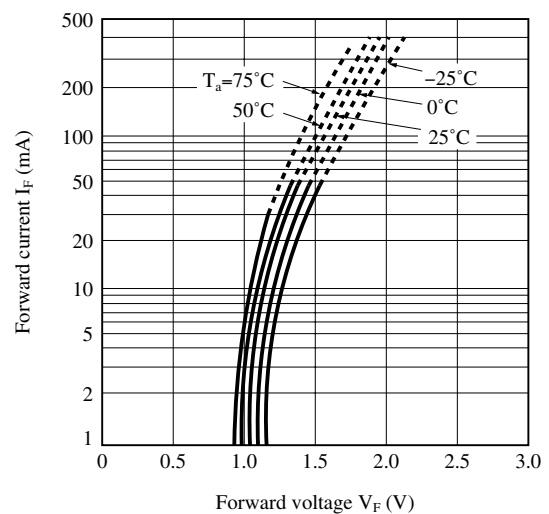


Fig.7 Current Transfer Ratio vs. Forward Current

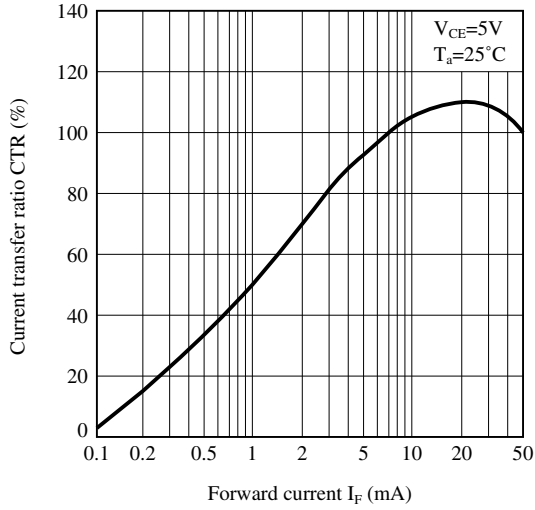


Fig.8 Collector Current vs. Collector-emitter Voltage

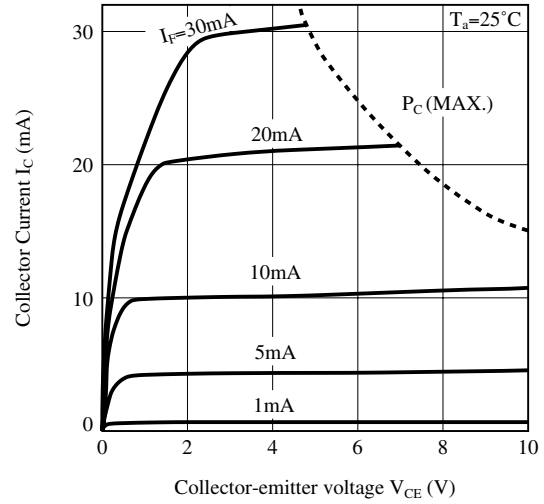


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

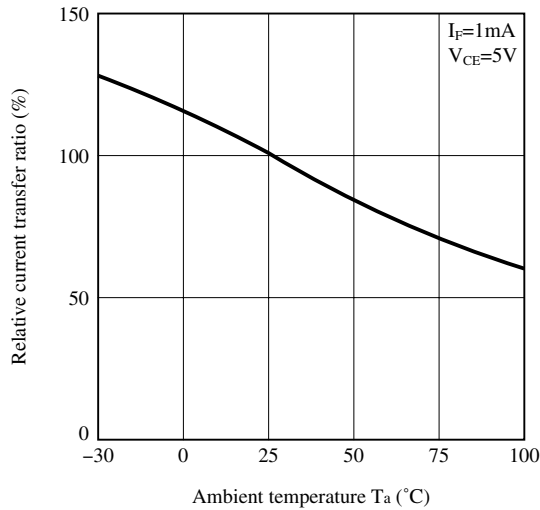


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

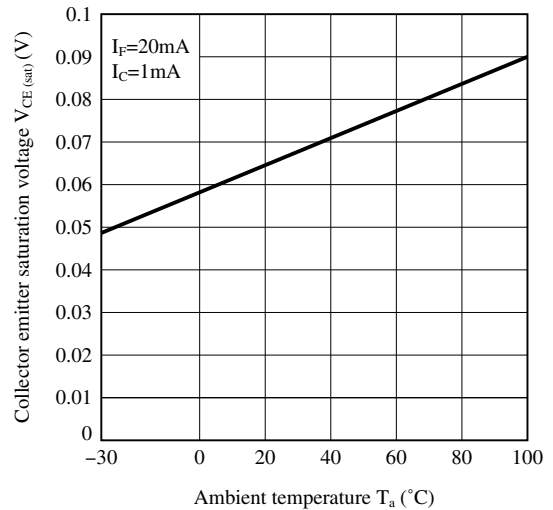


Fig.11 Collector Dark Current vs. Ambient Temperature

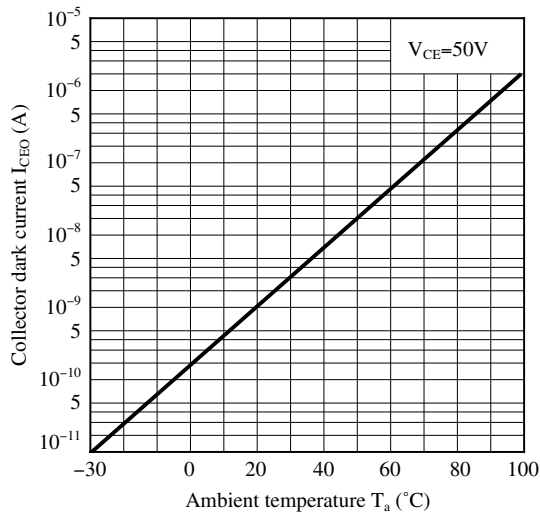


Fig.12 Collector-emitter Saturation Voltage vs. Forward Current

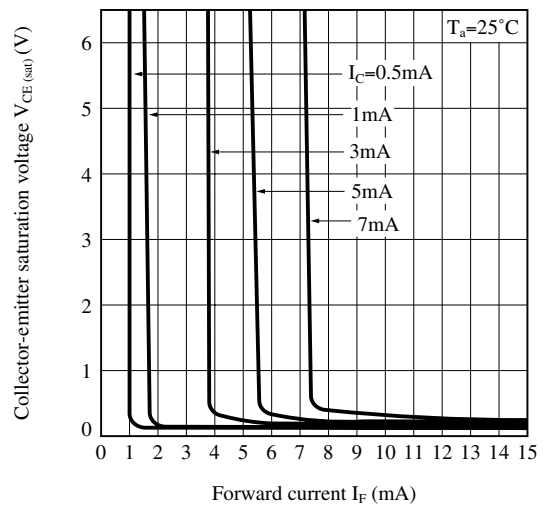


Fig.13 Response Time vs. Load Resistance

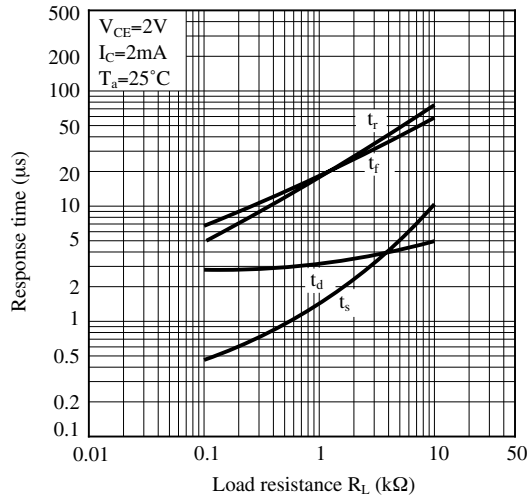
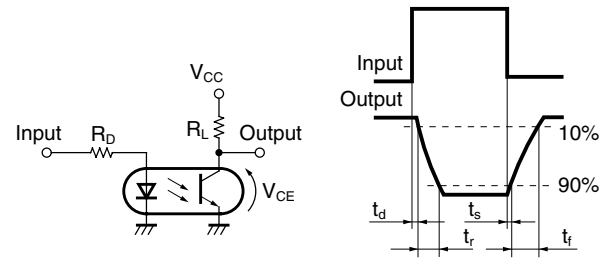


Fig.14 Test Circuit for Response Time



Please refer to the conditions in Fig.13.

Fig.15 Frequency Response

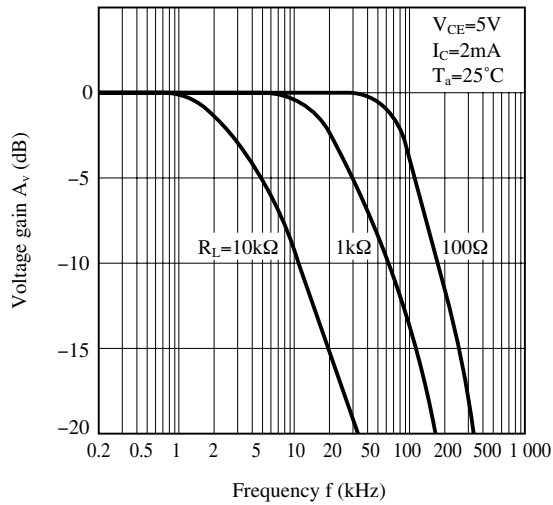
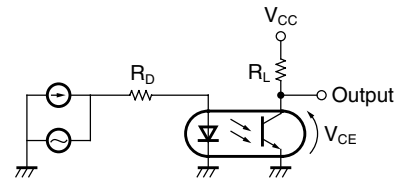


Fig.16 Test Circuit for Frequency Response



Please refer to the conditions in Fig.15.

Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ **Design Considerations**

● **Design guide**

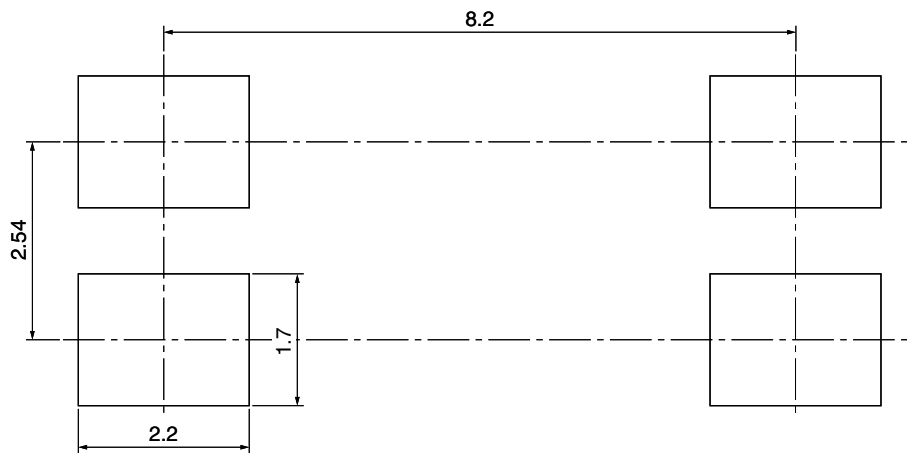
While operating at $I_F < 1.0\text{mA}$, CTR variation may increase.
Please make design considering this fact.

This product is not designed against irradiation and incorporates non-coherent IRED.

● **Degradation**

In general, the emission of the IRED used in photocouplers will degrade over time.
In the case of long term operation, please take the general IRED degradation (50% degradation over 5years) into the design consideration.

● **Recommended Foot Print (reference)**



(Unit : mm)

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

■ Manufacturing Guidelines

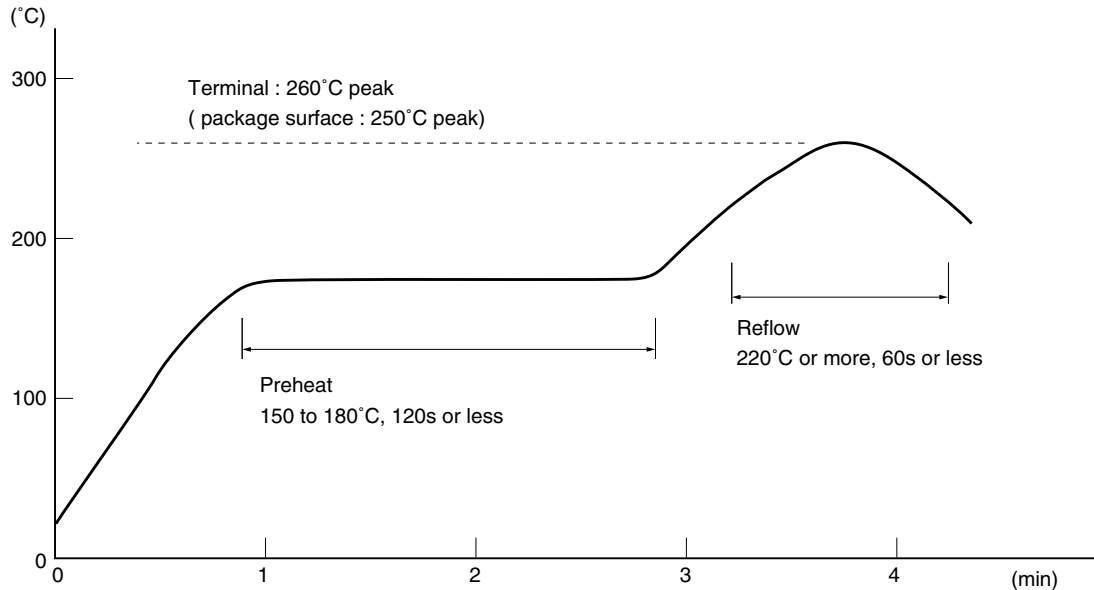
● Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.

● Cleaning instructions**Solvent cleaning:**

Solvent temperature should be 45°C or below Immersion time should be 3minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances:CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

■ **Package specification**

● **Sleeve package**

Package materials

Sleeve : HIPS (with anti-static material)

Stopper : Styrene-Elastomer

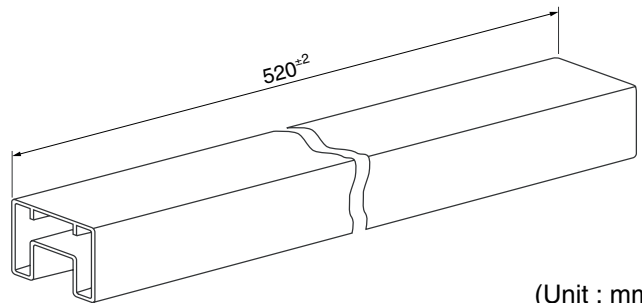
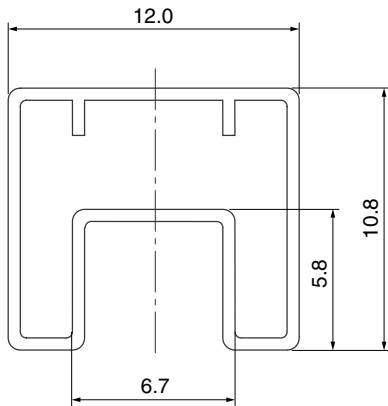
Package method

MAX. 100pcs of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.

The product shall be arranged in the sleeve with its primary side mark on the tabless stopper side.

MAX. 20 sleeves in one case.

Sleeve outline dimensions



(Unit : mm)

● Tape and Reel package

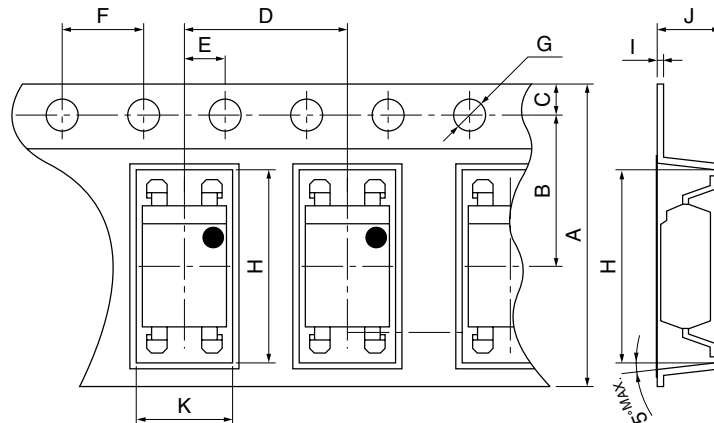
Package materials

Carrier tape : PS

Cover tape : PET (three layer system)

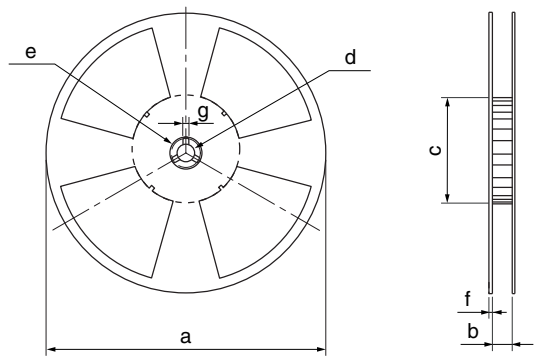
Reel : PS

Carrier tape structure and Dimensions



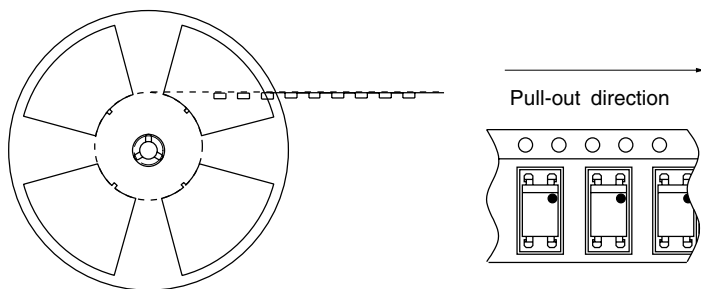
Dimensions List							(Unit : mm)
A	B	C	D	E	F	G	
16.0±0.3	7.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	φ1.5±0.1	
H	I	J	K				
10.4±0.1	0.4±0.05	4.2±0.1	5.1±0.1				

Reel structure and Dimensions



Dimensions List				(Unit : mm)
a	b	c	d	
330	17.5±1.5	100±1.0	13±0.5	
e	f	g		
23±1.0	2.0±0.5	2.0±0.5		

Direction of product insertion



[Packing : 2 000pcs/reel]

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

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- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

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